Market News

“Driving decarbonization and digitalization. Together.”: At MWC 2023 Infineon is showcasing its latest semiconductor technologies for a comfier and greener IoT

Munich, Germany – 17 February, 2023 – IoT technologies have the potential to overcome many of the challenges society faces today. Even more, they improve the quality of life, convenience and increase industrial productivity. At the heart of every IoT solution are microelectronics such as sensors, actuators, microcontrollers, connectivity modules and security components. Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) offers all of them and will present these building blocks, complemented by various services, software, and tools, to visitors at Mobile World Congress 2023 in Barcelona, from February 27 to March 2. As a leading semiconductor manufacturer for power systems and IoT solutions, Infineon is working with customers and partners to jointly drive decarbonization and digitalization.

Under the motto “Driving decarbonization and digitalization. Together.”, Infineon anticipates the opportunity to extend a personal welcome to their customers again this year. In addition, customers can register for Infineon’s digital platform – the perfect place to dive deeper into the various technologies that will be presented at MWC during and after the event. The Infineon booth in Hall 5a (booth #51) includes several focus areas:

- **Enabling a healthy life with smart semiconductor solutions**
  Infineon's semiconductor products are the perfect match for smart health devices as they meet the requirements of digital health devices. They support a health-conscious lifestyle by enabling smart home devices that can help improve well-being. For example, smart speakers with radar sensors can detect a heart beat, whether someone has fallen on the floor, and even coughing or snoring. In this way, Infineon's solutions enable not only a more comfortable, but also a longer, more independent and healthier life at home in an increasingly ageing society.

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- **Bringing AR to enterprise and medical environments**
  Magic Leap 2, the latest AR device from AR pioneer Magic Leap, is specifically designed for enterprise and healthcare applications. One of the key features of the latest Magic Leap generation is the 3D depth sensor technology with indirect light time-of-flight (iToF), jointly developed by Infineon and pmdtechnologies. The new and improved iToF technology connects the real and digital worlds more intuitively through improved gesture control and more accurate user interaction. This opens up new use cases where precision and reliability are critical, such as remote maintenance and diagnostics of industrial machinery, or AI-assisted surgery that enables doctors to better understand patient anatomy.

- **Decarbonizing data centers for a greener future**
  As more and more devices are connected in smart homes and other areas, it is estimated that 175 zettabytes of data will be processed globally by 2025. This will dramatically increase the energy needs of the world's 8,000 or so data centres, particularly for cooling servers. At MWC 23, Infineon is demonstrating together with Super Micro Computer how green computing platforms can make an important contribution to the decarbonization of computing. The MicroBlade® family offers top-notch server density for a wide range of processors and features integrated OptiMOS™ power stages with best-in-class efficiency.

- **Transforming things into payment devices**
  Why only pay with your credit card, smartphone, or smartwatch? Infineon's technology is helping to digitize payments by transforming virtually everything from smartwatches and fitness trackers to rings, bracelets and more into a payment device. This is possible with a chip half the size of a ladybug. At MWC 23, Infineon will demonstrate how ultra-low power consumption and tiny form factors are paving the way for a whole new dimension of NFC-enabled wearables for fast, convenient, and secure payments that meet the increasingly demanding security and contactless requirements of the payment industry.

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Infineon and adidas showcase smart and interactive jacket

At this year's Mobile World Congress in Barcelona, Infineon invited adidas AG to showcase their prototype of an interactive, smart jacket at the Infineon booth.The '5G Connected Sport Jacket' by adidas AG allows real-time feedback on fitness data, connectivity anytime and anywhere, as well as a SOS alarm system in case of emergency. Such applications embedded in clothes or any other wearable devices rely on semiconductor technology to turn a jacket into a smart device in order to avoid any other kind of mobile device while doing sports.

Infineon at Mobile World Congress 2023

Mobile World Congress 2023 will be held in Barcelona, Spain, from February 27 to March 2, 2023. Under the motto "Driving decarbonization and digitalization. Together.", Infineon will demonstrate in Hall 5a, Booth #51 and virtually how the latest semiconductor innovations are transforming smart homes, smart factories and wireless infrastructures. Information about the MWC show highlights is available at www.infineon.com/mwc.

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